



Material Content Data Sheet



Sales Product Name		BGA 614 H6327		Issued		5. May 2016		
MA#		MA000808602						
Package		PG-SOT343-4-2		Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		405	
	non noble metal	tin	7440-31-5	0.001	0.01		104	
	inorganic material	silicon	7440-21-3	0.021	0.30	0.35	3001	3510
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.55	49.76	495528	497619
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1482	1482
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4374	
	plastics	epoxy resin	-	0.652	9.40		94045	
	inorganic material	silicondioxide	60676-86-0	2.349	33.90	43.74	338998	437417
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28757	28757
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31215	31215
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com